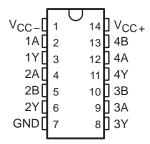
- Bi-MOS Technology With TTL and CMOS Compatibility
- Meets or Exceeds the Requirements of ANSI EIA/TIA-232-E and ITU Recommendation V.28
- Very Low Quiescent Current . . . 95 μA Typ V<sub>CC±</sub> = ±12 V
- Current-Limited Outputs . . . 10 mA Typ
- CMOS-and TTL-Compatible Inputs
- On-Chip Slew Rate Limited to 30 V/μs max
- Flexible Supply Voltage Range
- Characterized at V<sub>CC±</sub> of ±4.5 V and ±15 V
- Functionally Interchangeable With Texas Instruments SN75188, Motorola MC1488, and National Semiconductor DS14C88

### D, DB<sup>†</sup>, OR N PACKAGE (TOP VIEW)



† The DB package is only available left-end taped and reeled, i.e., order device SN75C188DBLE.

### description

The SN75C188 is a monolithic, low-power, quadruple line driver that interfaces data terminal equipment with data communications equipment. This device is designed to conform to ANSI Standard EIA/TIA-232-E.

An external diode in series with each supply-voltage terminal is needed to protect the SN75C188 under certain fault conditions to comply with EIA/TIA-232-E.

The SN75C188 is characterized for operation from 0°C to 70°C.

#### **Function Tables**

| DRIVER 1 |   |  |  |  |  |  |  |
|----------|---|--|--|--|--|--|--|
| В        | Υ |  |  |  |  |  |  |
| Н        | L |  |  |  |  |  |  |
| L        | Н |  |  |  |  |  |  |

DRIVERS 2 - 4

| Α | В | Υ |
|---|---|---|
| Н | Н | L |
| L | X | Н |
| Х | L | Н |

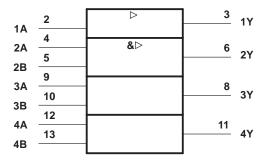
H = high level, L = low level, X = don't care



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

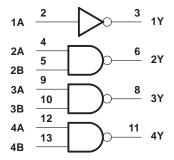


# logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

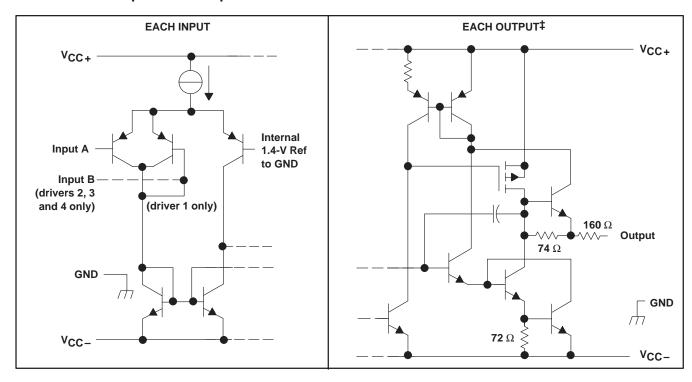
# logic diagram (positive logic)



positive logic

 $Y = \overline{A} (driver 1)$   $Y = \overline{AB} \text{ or } \overline{A} + \overline{B} (drivers 2 \text{ through 4})$ 

# schematics of inputs and outputs



<sup>‡</sup> All resistor values shown are nominal.



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V <sub>CC+</sub> (see Note 1)                | 15 V                                  |
|--|---------------------------------------|
| Supply voltage, V <sub>CC</sub> (see Note 1)                 |                                       |
| Input voltage range, V <sub>I</sub>                          | V <sub>CC</sub> - to V <sub>CC+</sub> |
| Output voltage range, VO                                     | $V_{CC-}$ –6 V to $V_{CC+}$ +6 V      |
| Continuous total power dissipation                           | See Dissipation Rating Table          |
| Operating free-air temperature range, T <sub>A</sub>         | 0°C to 70°C                           |
| Storage temperature range, T <sub>stq</sub>                  | 65°C to 150°C                         |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds |                                       |

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the network ground terminal.

#### **DISSIPATION RATING TABLE**

| PACKAGE | T <sub>A</sub> ≤ 25°C<br>POWER RATING | DERATING FACTOR<br>ABOVE T <sub>A</sub> = 25°C | T <sub>A</sub> = 70°C<br>POWER RATING |  |  |  |
|---------|---------------------------------------|--|---------------------------------------|--|--|--|
| D       | 950 mW                                | 7.6 mW/°C                                      | 608 mW                                |  |  |  |
| DB      | 525 mW                                | 4.2 mW/°C                                      | 336 mW                                |  |  |  |
| N       | 1150 mW                               | 9.2 mW/°C                                      | 736 mW                                |  |  |  |

# recommended operating conditions

|  | MIN                 | NOM | MAX              | UNIT |
|--|---------------------|-----|------------------|------|
| Supply voltage, V <sub>CC+</sub>               | 4.5                 | 12  | 15               | V    |
| Supply voltage, V <sub>CC</sub> _              | -4.5                | -12 | -15              | V    |
| Input voltage, V <sub>I</sub>                  | V <sub>CC</sub> -+2 |     | V <sub>CC+</sub> | V    |
| High-level Input voltage, VIH                  | 2                   |     |                  | V    |
| Low-level Input voltage, V <sub>IL</sub>       |                     |     | 0.8              | V    |
| Operating free-air temperature, T <sub>A</sub> | 0                   |     | 70               | °C   |



# electrical characteristics over operating free-air temperature range, $V_{CC+} = 12 \text{ V}$ , $V_{CC-} = -12 \text{ V}$ (unless otherwise noted)

|                 | PARAMETER                                |                                     | TEST CONDIT              | MIN  | TYP <sup>†</sup> | MAX | UNIT  |    |
|-----------------|--|-------------------------------------|--------------------------|--|------------------|-----|-------|----|
| V <sub>ОН</sub> | High-level output voltage                | V <sub>II</sub> = 0.8 V,            | $R_1 = 3 k\Omega$        | V <sub>CC+</sub> = 5 V,<br>V <sub>CC-</sub> = -5 V   | 4                |     |       | V  |
| VOH             | r ngr-lever output voltage               | VIL = 0.0 V,                        | N_ = 3 K22               | V <sub>CC+</sub> = 12 V,<br>V <sub>CC-</sub> = -12 V | 10               |     |       | V  |
| Voi             | Low-level output voltage                 | V <sub>IH</sub> = 2 V,              | $R_1 = 3 k\Omega$        | V <sub>CC+</sub> = 5 V,<br>V <sub>CC-</sub> = -5 V   |                  |     | -4    | ٧  |
| VOL             | (see Note 2)                             | VIH - 2 v,                          | N_ = 3 N22               | V <sub>CC+</sub> = 12 V,<br>V <sub>CC-</sub> = -12 V |                  |     | -10   | v  |
| lН              | High-level input current                 | V <sub>I</sub> = 5 V                |                          |  |                  |     | 10    | μΑ |
| IIL             | Low-level input current                  | V <sub>I</sub> = 0                  |                          |  |                  |     | -10   | μΑ |
| IOS(H)          | High-level short-circuit output current‡ | V <sub>I</sub> = 0.8 V,             | VO = 0 or VCC-           |  | -5.5             | -10 | -19.5 | mA |
| IOS(L)          | Low-level short-circuit output current‡  | V <sub>I</sub> = 2 V,               | $V_O = 0$ or $V_{CC} +$  |  | 5.5              | 10  | 19.5  | mA |
| rO              | Output resistance, power off             | $V_{CC+} = 0$ ,                     | V <sub>CC</sub> -= 0,    | $V_I = -2 V \text{ to } 2 V$                         | 300              |     |       | Ω  |
| laa             | Supply current from V <sub>CC+</sub>     | V <sub>CC+</sub> = 5 V,<br>No load  | V <sub>CC</sub> -=-5 V,  | All inputs at 2 V or 0.8 V                           |                  | 90  | 160   | μA |
| ICC+            | Supply carrent from vCC+                 | V <sub>CC+</sub> = 12 V,<br>No load | V <sub>CC</sub> -=-12 V, | All inputs at 2 V or 0.8 V                           |                  | 95  | 160   | μΑ |
| loo             | Supply current from Voc                  | V <sub>CC+</sub> = 5 V,<br>No load  | V <sub>CC</sub> -=-5 V,  | All inputs at 2 V or 0.8 V                           |                  | -90 | -160  |    |
| Icc-            | Supply current from V <sub>CC</sub> _    | V <sub>CC+</sub> = 12 V,<br>No load | V <sub>CC</sub> -=-12    | All inputs at 2 V or 0.8 V                           |                  | -95 | -160  | μА |

<sup>†</sup> All typical values are at  $T_A = 25$ °C.

NOTE 2: The algebraic convention, in which the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only; e.g., if  $-4\ V$  is a maximum, the typical value is a more negative voltage.

# switching characteristics, $V_{CC+}$ = 12 V, $V_{CC-}$ = -12 V, $T_A$ = 25°C

|                  | PARAMETER  | TEST CON                                | MIN                       | TYP  | MAX | UNIT |      |
|------------------|--|---|---------------------------|------|-----|------|------|
| tPLH             | Propagation delay time, low- to high-level output§ | $R_L = 3 k\Omega$ ,                     | C <sub>L</sub> = 15 pF,   |      |     | 3    | μs   |
| t <sub>PHL</sub> | Propagation delay time, high- to low-level output§ | See Figure 1                            |                           |      |     | 3.5  | μs   |
| tTLH             | Transition time, low- to high-level output         |   |                           | 0.53 |     | 3.2  | μs   |
| <sup>t</sup> THL | Transition time, high- to low-level output         |   |                           | 0.53 |     | 3.2  | μs   |
| tTLH             | Transition time, low- to high-level output#        | $R_L = 3 k\Omega$ to $7 k\Omega$ ,      | C <sub>L</sub> = 2500 pF, |      | 1.5 |      | μs   |
| <sup>t</sup> THL | Transition time, high- to low-level output#        | See Figure 1                            |                           |      | 1.5 |      | μs   |
| SR               | Output slew rate§                                  | $R_L = 3 k\Omega \text{ to } 7 k\Omega$ | C <sub>L</sub> = 15 pF    | 6    | 15  | 30   | V/μs |

<sup>§</sup> Measured at the 50% level

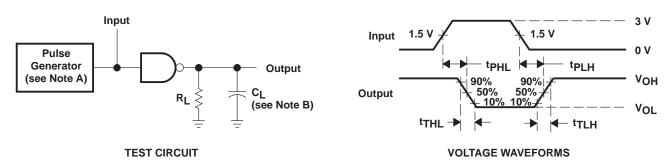


<sup>‡</sup> Not more than one output should be shorted at a time.

<sup>¶</sup> Measured between the 10% and 90% points on the output waveform

<sup>#</sup> Measured between the 3-V and -3-V points on the output waveform (EIA/TIA-232-E conditions), all unused inputs tied either high or low

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics:  $t_W$  = 25  $\mu$ s, PRR = 20 kHZ,  $Z_O$  = 50  $\Omega$ ,  $t_f$  =  $t_f$   $\leq$  50 ns.

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms

### TYPICAL CHARACTERISTICS

#### **VOLTAGE TRANSFER CHARACTERISTICS** 15 $V_{CC\pm} = \pm 15 V$ V<sub>CC±</sub> = ±12 V 12 $V_{CC\pm} = \pm 9 V$ 9 V<sub>O</sub> - Output Voltage - V $V_{CC\pm} = \pm 5 V$ 6 3 0 $V_{CC\pm} = \pm 5 V$ -3-6 $V_{CC\pm} = \pm 9 V$ $V_{CC\pm} = \pm 12 V$ -9 $R_L = 3 k\Omega$ $V_{CC\pm}$ = $\pm 5$ V -12T<sub>A</sub> = 25°C 0.2 0.4 0.6 0.8 1 1.2 1.4 1.6 1.8 0 VI - Input Voltage - V

Figure 2

# SHORT-CIRCUIT OUTPUT CURRENT FREE-AIR TEMPERATURE 15 $V_{CC\pm} = \pm 12 V$ IOS - Short-Circuit Output Current - mA 10 I<sub>OS(L)</sub> V<sub>I</sub> = 2 V 5 $V_O = 0$ or $V_{CC+}$ 0 -5 $I_{OS(H)}$ $V_{I} = 0.8 V$ $V_O = 0$ or $V_{CC}$ -10-1520 60 80 100 120 T<sub>A</sub> - Free-Air Temperature - °C

Figure 4

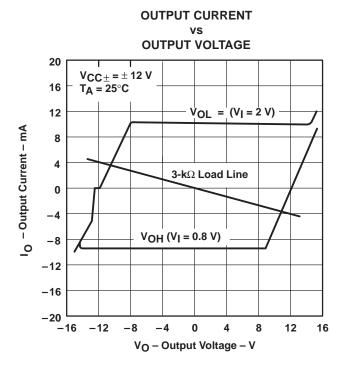
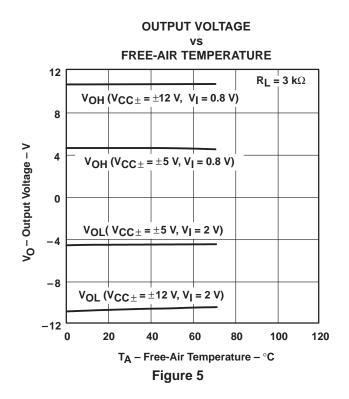
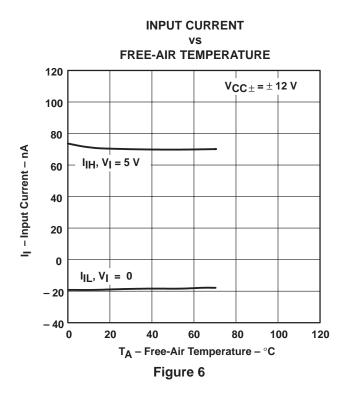


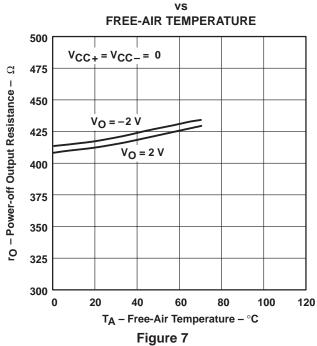
Figure 3

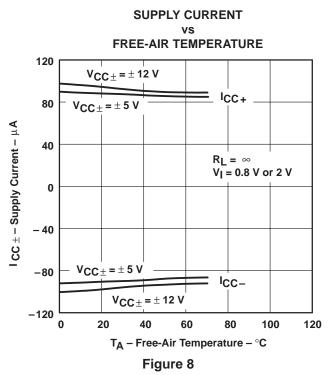


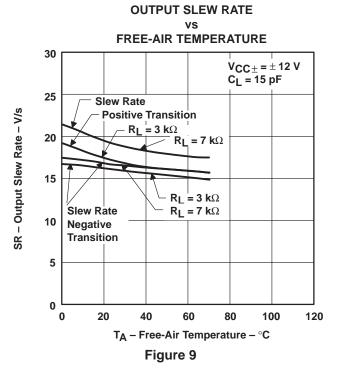
**POWER-OFF OUTPUT RESISTANCE** 

### **TYPICAL CHARACTERISTICS**

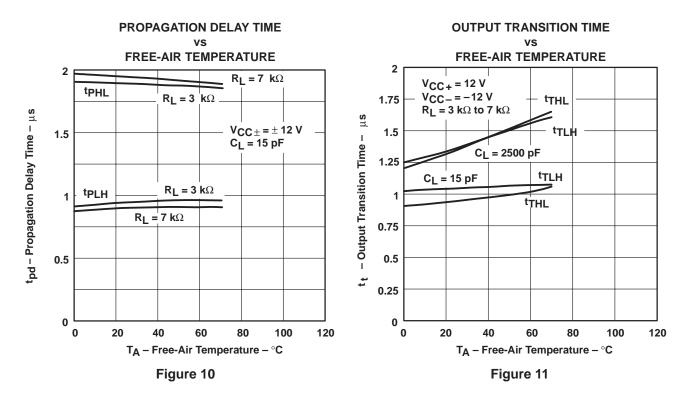








### TYPICAL CHARACTERISTICS



### **APPLICATION INFORMATION**

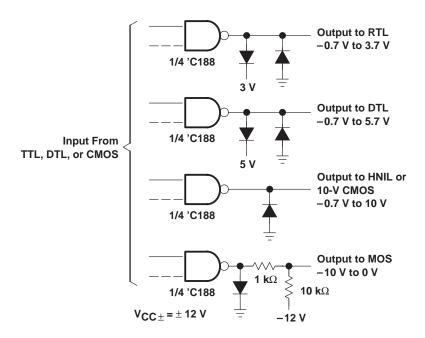
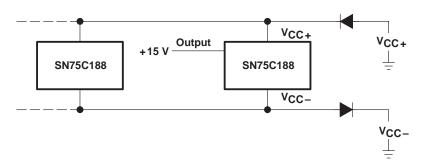


Figure 12. Logic Translator Applications



### **APPLICATION INFORMATION**



NOTE A: External diodes placed in series with the  $V_{CC-}$  and  $V_{CC-}$  leads protect the SN75C188 in the fault condition where the device outputs are shorted to  $\pm$ 15 V and the power supplies are at low voltage and provide low-impedance paths to GND.

Figure 13. Power Supply Protection to Meet Power-Off Fault Conditions of Standard EIA/TIA-232-E







10-Dec-2020

#### PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan     | Lead finish/<br>Ball material | MSL Peak Temp      | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|------------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|----------------------|---------|
| SN75C188D        | ACTIVE     | SOIC         | D                  | 14   | 50             | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | SN75C188             | Samples |
| SN75C188DBR      | ACTIVE     | SSOP         | DB                 | 14   | 2000           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | CA188                | Samples |
| SN75C188DR       | ACTIVE     | SOIC         | D                  | 14   | 2500           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | SN75C188             | Samples |
| SN75C188DRE4     | ACTIVE     | SOIC         | D                  | 14   | 2500           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | SN75C188             | Samples |
| SN75C188N        | ACTIVE     | PDIP         | N                  | 14   | 25             | RoHS & Green | NIPDAU                        | N / A for Pkg Type | 0 to 70      | SN75C188N            | Samples |
| SN75C188NSR      | ACTIVE     | SO           | NS                 | 14   | 2000           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | 75C188               | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



# **PACKAGE OPTION ADDENDUM**

10-Dec-2020

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# PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width     |
|----|---|
|    | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

| All diffierisions are nomina |                 |                    |    |      |                          |                          |            |            |            |            |           |                  |
|------------------------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device                       | Package<br>Type | Package<br>Drawing |    | SPQ  | Reel<br>Diameter<br>(mm) | Reel<br>Width<br>W1 (mm) | A0<br>(mm) | B0<br>(mm) | K0<br>(mm) | P1<br>(mm) | W<br>(mm) | Pin1<br>Quadrant |
| SN75C188DBR                  | SSOP            | DB                 | 14 | 2000 | 330.0                    | 16.4                     | 8.35       | 6.6        | 2.4        | 12.0       | 16.0      | Q1               |
| SN75C188DR                   | SOIC            | D                  | 14 | 2500 | 330.0                    | 16.4                     | 6.5        | 9.0        | 2.1        | 8.0        | 16.0      | Q1               |
| SN75C188DR                   | SOIC            | D                  | 14 | 2500 | 330.0                    | 16.4                     | 6.5        | 9.0        | 2.1        | 8.0        | 16.0      | Q1               |
| SN75C188NSR                  | SO              | NS                 | 14 | 2000 | 330.0                    | 16.4                     | 8.2        | 10.5       | 2.5        | 12.0       | 16.0      | Q1               |

**PACKAGE MATERIALS INFORMATION** 

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\*All dimensions are nominal

| 7 till dillitoriororio di o riorimital |              |                 |      |      |             |            |             |
|--|--------------|-----------------|------|------|-------------|------------|-------------|
| Device                                 | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
| SN75C188DBR                            | SSOP         | DB              | 14   | 2000 | 853.0       | 449.0      | 35.0        |
| SN75C188DR                             | SOIC         | D               | 14   | 2500 | 853.0       | 449.0      | 35.0        |
| SN75C188DR                             | SOIC         | D               | 14   | 2500 | 333.2       | 345.9      | 28.6        |
| SN75C188NSR                            | SO           | NS              | 14   | 2000 | 853.0       | 449.0      | 35.0        |

# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# DB (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE

### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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